

6th INTERNATIONAL ELECTRONIC CIRCUIT PACKAGING SYMPOSIUM

HILTON HOTEL ■ AUGUST 23-24, 1965 ■ SAN FRANCISCO, CALIFORNIA

A NON-PROFIT, NON-COM-MERCIAL PROGRAM OF TECHNICAL INFORMATION FOR ALL WHO WORK IN ELECTRONIC PACKAGING DESIGN, ENGINEERING AND PRODUCTION AND APPLICATION

PURPOSE

The purpose of the Symposium is to provide a forum for the free exchange of concepts and ideas between engineers working in all phases of electronic packaging from pure research to ultimate application. The Symposium has become the recognized forum in the field of electronic packaging and has attracted attendees and program participants from around the world.

PROGRAM

SESSION I: LASERS AT WORK IN ELECTRONIC PACKAGING

Monday, August 23, 1965—10:00 a.m.

"LASER WELDING IN ELECTRONIC CIRCUIT FABRICATION"

J. P. Epperson—Western Electric

"PRACTICAL APPLICATIONS OF LASER WELDING"

J. Martin—Hughes Aircraft

SESSION II: PACKAGING FOR HIGH SPEED ELECTRONIC SYSTEMS

Monday, August 23, 1965—1:30 p.m.

"CIRCUIT PACKAGING FOR HIGH SPEED PULSES"

F. A. Karner—IBM, Gen. Prod. Div.

"A MULTIPLE SIGNAL PLUGGABLE CONNECTOR FOR A HIGH-SPEED COMPUTER SYSTEM"

J. S. Harris, W. Radzelovage, W. L. Springfield—IBM

"PROPAGATION CHARACTERISTICS OF INHOMOGENEOUS MULTICONDUCTOR TRANSMISSION LINES"

A. Shah—IBM, Gen. Prod. Div.

SESSION III: INTERCONNECTION TECHNOLOGY

Monday, August 23, 1965—3:00 p.m.

"A NEW RELIABLE PRINTED WIRING THRU-CONNECTION"

J. A. Burns—Western Electric • G. Eftang—Bell Telephone Labs.

"NEW APPROACHES TO HIGH DENSITY MODULE INTERCONNECTIONS"

L. Fiderer—Hughes Aircraft Co.

"RECENT RESEARCH IN THE SCIENCE OF ELECTRIC CONNECTORS"

J. B. P. Williamson—Burndy Corp.

"DEVELOPMENT OF A NON-DESTRUCTIVE INSPECTION TECHNIQUE FOR WELDED ELECTRICAL CONNECTIONS"

W. C. Croucher—Martin Company

ADVANCE REGISTRATION

6th International Electronic Circuit Packaging Symposium
Hilton Hotel San Francisco August 23-24

COMPLETE AND MAIL WITH YOUR CHECK TO:

6TH INT. ELECTRONIC CIRCUIT PACKAGING SYMPOSIUM
P. O. BOX 155
ENGLEWOOD, COLORADO 80110



Check for \$35.00 enclosed includes registration for all symposium sessions, luncheons August 23-24, copy of the 1965 Symposium Proceedings, complimentary WESCON registration. This advance registration will be confirmed.

Please circle the sessions you plan to attend:

1 2 3 4 5

Please send the following information about the Symposium...

NAME

TITLE

ORGANIZATION

ADDRESS

CITY

STATE

ZIP CODE

CHECKS ONLY PLEASE, MAKE PAYABLE TO 6th INTERNATIONAL ELECTRONIC CIRCUIT PACKAGING SYMPOSIUM

PROGRAM

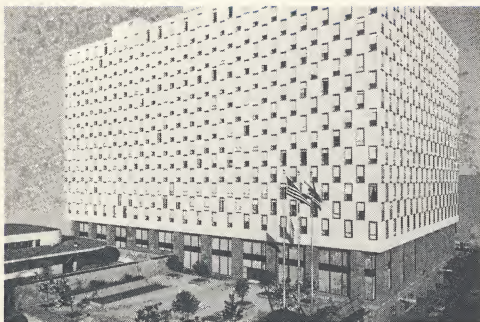
The symposium's two day program is built around a series of technical papers selected by a national committee of experts in the field. Attendees receive advance copies of the papers. The time allotted for presentation of each paper is divided into two parts. During the first part, each author will present highlights of the paper (not read it), show pertinent slides, and give his personal insight into the problem and its solutions. The second part of the presentation is thrown open for discussion—questions and answers between speakers and attendees.

EVENTS FOR WIVES

Events for wives are scheduled by WESCON. The many fascinating aspects of San Francisco guarantee that there will be no symposium widows. Literature describing San Francisco will be available at the Symposium.

ADVANCED REGISTRATION

Advance registration for the 6th International Electronic Circuit Packaging Symposium is possible by using the attached form. The \$35.00 registration fee (payable by check only) includes: 1) Attendance at all sessions of the Symposium 2) Luncheon on August 23 and August 24th 3) One copy of the Proceedings of the Symposium (1964 Proceeding's price: \$18.00). 4) Complimentary WESCON registration (normally \$2.00).



**SAN FRANCISCO HILTON HOTEL,
SCENE OF THIS YEAR'S**



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WESCON/65

SESSION IV: MICROELECTRONIC PACKAGING TECHNIQUES

Tuesday, August 24, 1965—9:00 a.m.

"LEAD ATTACHMENT TO THIN FILM CIRCUITS"

J. Avila, G. E. Klienedler—Western Electric

"MICRO-MATRIX: A NEW CONCEPT IN INTERCONNECTION FOR INTEGRATED CIRCUITS"

S. Walker—Motorola

"THERMAL ANALYSIS OF HYBRID MICROCIRCUITS"

D. Burke—Sprague Electric

"A HIGH DENSITY MULTILAYER PRINTED WIRING INTRACONNECTION SYSTEM"

J. C. Eckhardt, W. L. Yessa—Automatic Electric

"TWO DIMENSIONAL VS. THREE DIMENSIONAL PACKAGING OF INTEGRATED CIRCUITS"

G. Rapprecht, E. Stubler—Motorola

"A COMPARISON OF PARALLEL-GAP WELDED & PARALLEL-GAP SOLDERED INTERCONNECTIONS FOR INTEGRATED CIRCUITS"

G. A. Dreyer & F. Z. Keister—Hughes Aircraft

SESSION V: PACKAGING MICROELECTRONIC SYSTEMS

Tuesday, August 24, 1965—1:30 p.m.

"MICROELECTRONICS PACKAGING FOR DIGITAL GROUND SYSTEMS"

J. W. Sullivan—Philco

"SYSTEM DESIGN FOR ANALOG MICROMINIATURIZATION"

F. Basset, M. Ohanian—Raytheon

"MECHANICAL DESIGN CONSIDERATIONS FOR A COMMERCIAL INTEGRATED CIRCUIT DIGITAL COMPUTER"

R. Lawrence—Bunker-Ramo

"PACKAGING DESIGN FOR A GENERAL PURPOSE COMPUTER"

M. J. Berberian—Sylvania Electronic Systems

"HYBRID MICROELECTRONIC DESIGN FOR OPTIMUM PERFORMANCE"

D. W. Thompson—Space Technology Labs.

"ALL WELDED MULTI-LAYER INTEGRATED CIRCUIT PACKAGING INNOVATIONS"

W. Johnson—Sperry Gyroscope

QUESTIONS AND ANSWERS ABOUT THE SYMPOSIUM

How about hotel reservations? These will be handled by the San Francisco Convention Bureau—a request form will be supplied with your registration confirmation. **Will purchase orders be accepted for advance registration?** No, checks or money orders only, please. **How much is registration for only one session?** \$35.00. **Will extra luncheon tickets be available?** Yes, they will be sold at the registration desk. **When will advance registration close?** On August 10th.